

CMOS 8-Stage Static Shift Registers

High-Voltage Types (20-Volt Rating)

CD4014B:

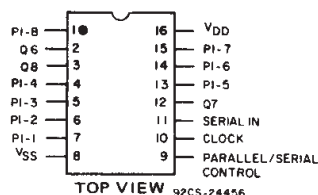
Synchronous Parallel or
Serial Input/Serial Output

CD4021B:

Asynchronous Parallel Input or
Synchronous Serial Input/Serial Output

■ CD4014B and CD4021B series types are 8-stage parallel- or serial-input/serial output registers having common CLOCK and PARALLEL/SERIAL CONTROL inputs, a single SERIAL data input, and individual parallel “JAM” inputs to each register stage. Each register stage is a D-type, master-slave flip-flop. In addition to an output from stage 8, “Q” outputs are also available from stages 6 and 7. Parallel as well as serial entry is made into the register synchronously with the positive clock line transition in the CD4014B. In the CD4021B serial entry is synchronous with the clock but parallel entry is asynchronous. In both types, entry is controlled by the PARALLEL/SERIAL CONTROL input. When the PARALLEL/SERIAL CONTROL input is low, data is serially shifted into the 8-stage register synchronously with the positive transition of the clock line. When the PARALLEL/SERIAL CONTROL input is high, data is jammed into the 8-stage register via the parallel input lines and synchronous with the positive transition of the clock line. In the CD4021B, the CLOCK input of the internal stage is “forced” when asynchronous parallel entry is made. Register expansion using multiple packages is permitted.

The CD4014B and CD4021B series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

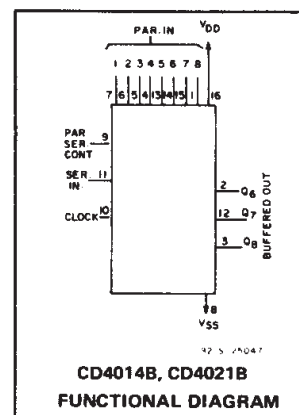


TOP VIEW 92CS-24456
**TERMINAL DIAGRAM
CD4014B, CD4021B**

CD4014B, CD4021B Types

Features:

- Medium-speed operation . . . 12 MHz (typ.) clock rate at $V_{DD}-V_{SS} = 10\text{ V}$
- Fully static operation
- 8 master-slave flip-flops plus output buffering and control gating
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) = 1 V at $V_{DD} = 5\text{ V}$
2 V at $V_{DD} = 10\text{ V}$
2.5 V at $V_{DD} = 15\text{ V}$
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, “Standard Specifications for Description of ‘B’ Series CMOS Devices”



**CD4014B, CD4021B
FUNCTIONAL DIAGRAM**

Applications:

- Parallel input/serial output data queueing
- Parallel to serial data conversion
- General-purpose register

RECOMMENDED OPERATING CONDITIONS AT $T_A = 25^\circ\text{C}$, Unless Otherwise Specified
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	V _{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (T _A = Full Package-Temperature Range)	—	3	18	V
Clock Pulse Width, t _W	5	180	—	ns
	10	80	—	
	15	50	—	
Clock Frequency, f _{CL}	5	—	3	MHz
	10	—	6	
	15	—	8.5	
Clock Rise and Fall Time, t _{rCL} , t _{fCL}	5	—	15	μs
	10	—	15	
	15	—	15	
Set-up Time, t _s :				
Serial Input (ref. to CL)	5	120	—	ns
	10	80	—	
	15	60	—	
Parallel Inputs CD4014B (ref. to CL)	5	80	—	ns
	10	50	—	
	15	40	—	
Parallel Inputs CD4021B (ref. to P/S)	5	50	—	ns
	10	30	—	
	15	20	—	
Parallel/Serial Control CD4014B (ref. to CL)	5	180	—	ns
	10	80	—	
	15	60	—	
Parallel/Serial Pulse Width, t _W (CD4021B)	5	160	—	ns
	10	80	—	
	15	50	—	
Parallel/Serial Removal Time, t _{REM} (CD4021B)	5	280	—	ns
	10	140	—	
	15	100	—	

CD4014B, CD4021B Types

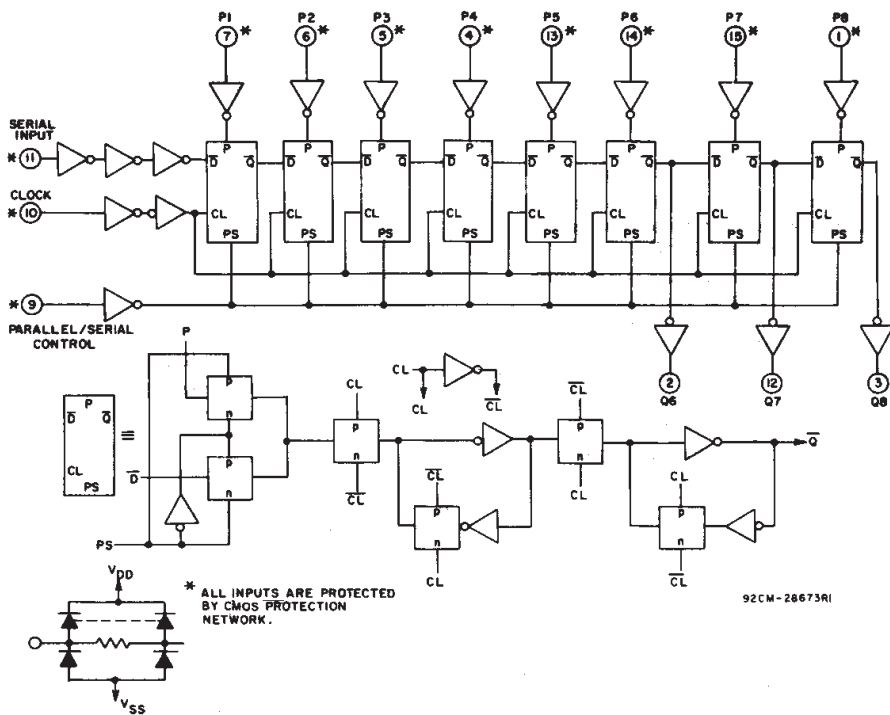


Fig. 1 - Logic diagram for CD4014B.

TRUTH TABLE - CD4014B

CL	SER IN	PAR SER CONTROL	Pi-1	Pi-n	Q1 (INTERNAL)	Qn
0	X	1	0	0	0	0
0	X	1	1	0	1	0
0	X	1	0	1	0	1
0	X	1	1	1	1	1
0	0	0	X	X	0	Qn-1
0	1	0	X	X	1	Qn-1
0	X	X	X	X	Q1	Qn

X = DON'T CARE CASE
NC = NO CHANGE

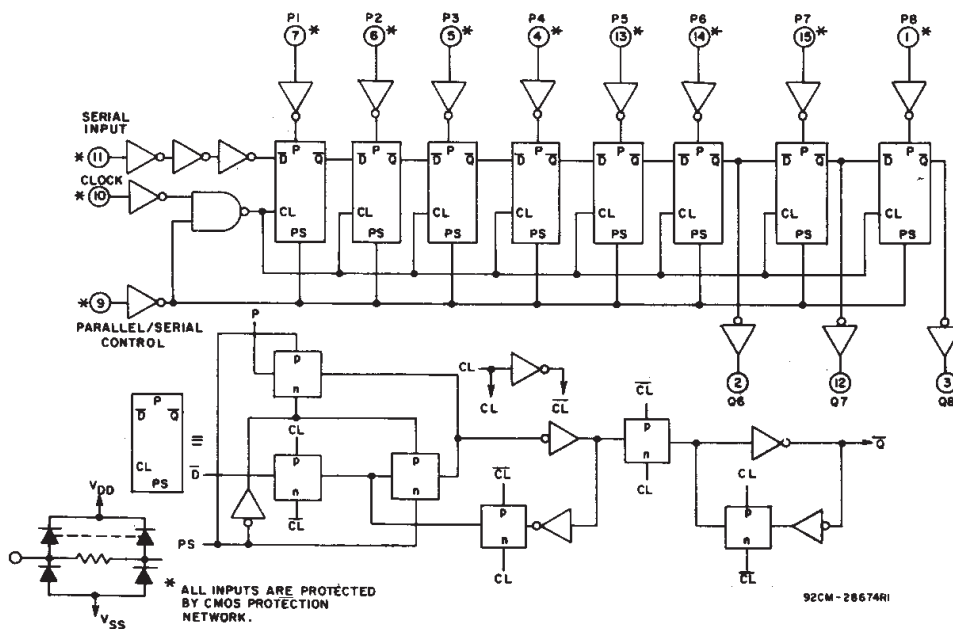


Fig. 2 - Logic diagram for CD4021B.

TRUTH TABLE - CD4021B

CL	Serial Input	Parallel/Serial Control	Pi-1	Pi-n	Q1 (Internal)	Qn
0	X	1	0	0	0	0
0	X	1	0	1	0	1
0	X	1	1	0	1	0
0	X	1	1	1	1	1
0	0	0	X	X	0	Qn-1
0	1	0	X	X	1	Qn-1
0	X	0	X	X	Q1	Qn

X = DON'T CARE CASE

CD4014B, CD4021B Types

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal) -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT $\pm 10\text{mA}$

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW

For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearity at $12\text{mW}/^\circ\text{C}$ to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to $+125^\circ\text{C}$

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance $1/16 \pm 1/32$ inch ($1.59 \pm 0.79\text{mm}$) from case for 10s max $+265^\circ\text{C}$

STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage V _{IL} Max.	0.5,4.5	—	5	1.5				—	—	1.5	V
	1,9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0.5,4.5	—	5	3.5				3.5	—	—	V
	1,9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

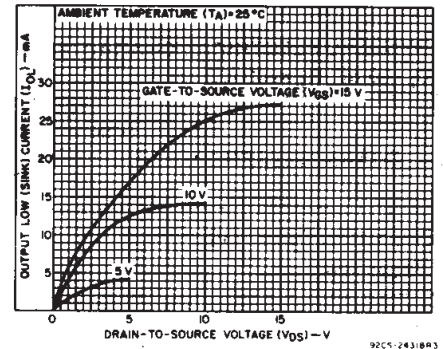


Fig. 3 - Typical output low (sink) current characteristics.

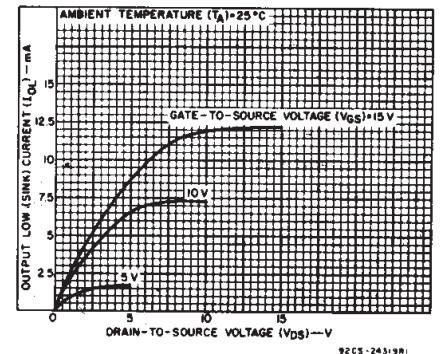


Fig. 4 - Minimum output low (sink) current characteristics.

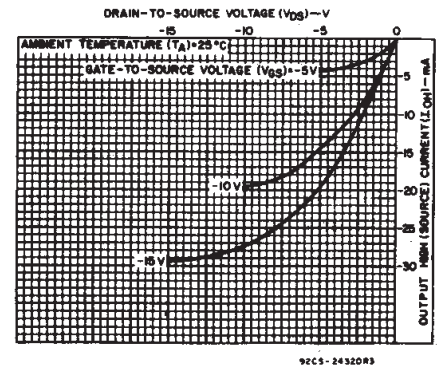


Fig. 5 - Typical output high (source) current characteristics.

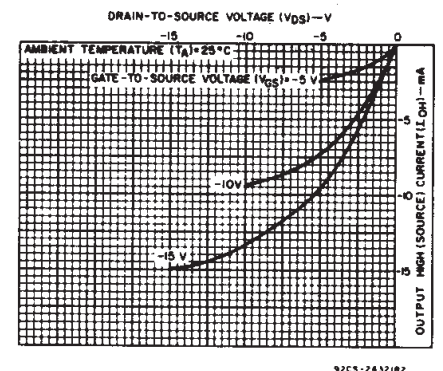


Fig. 6 - Minimum output high (source) current characteristics.

CD4014B, CD4021B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A=25^\circ\text{C}$, Input $t_r, t_f=20\text{ ns}$,
 $C_L=50\text{ pF}$, $R_L=200\text{ K}\Omega$

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
		V_{DD} (V)	Min.	Typ.	Max.
Propagation Delay Time, t_{PLH}, t_{PHL}		5	—	160	320
		10	—	80	160
		15	—	60	120
Transition Time, t_{THL}, t_{TLH}		5	—	100	200
		10	—	50	100
		15	—	40	80
Maximum Clock Input Frequency, f_{CL}		5	3	6	—
		10	6	12	—
		15	8.5	17	—
Minimum Clock Pulse Width, t_W		5	—	90	180
		10	—	40	80
		15	—	25	50
Clock Rise and Fall Time, t_{rCL}, t_{fCL}^*		5	—	—	15
		10	—	—	15
		15	—	—	15
Minimum Set-up Time, t_s : Serial Input (ref. to CL)		5	—	60	120
		10	—	40	80
		15	—	30	60
Parallel Inputs CD4014B (ref. to CL)		5	—	40	80
		10	—	25	50
		15	—	20	40
Parallel Inputs CD4021B (ref. to P/S)		5	—	25	50
		10	—	15	30
		15	—	10	20
Parallel/Serial Control CD4014B (ref. to CL)		5	—	90	180
		10	—	40	80
		15	—	30	60
Minimum Hold Time, t_H : Serial In, Parallel In, Parallel/Serial Control		5	—	—	0
		10	—	—	0
		15	—	—	0
Minimum P/S Pulse Width, t_{WH} (CD4021B)		5	—	80	160
		10	—	40	80
		15	—	25	50
Minimum P/S Removal Time, t_{REM} CD4021B (ref. to CL)		5	—	140	280
		10	—	70	140
		15	—	50	100
Average Input Capacitance, C_I	Any Input		—	5	7.5
					pF

* If more than one unit is cascaded t_{rCL} should be made less than or equal to the sum of the transition time and the fixed propagation delay of the output of the driving stage for the estimated capacitive load.

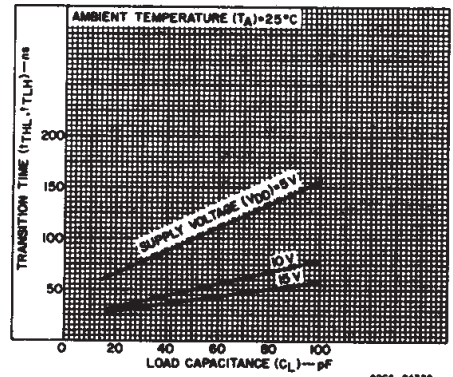


Fig. 7 - Typical transition time as a function of load capacitance.

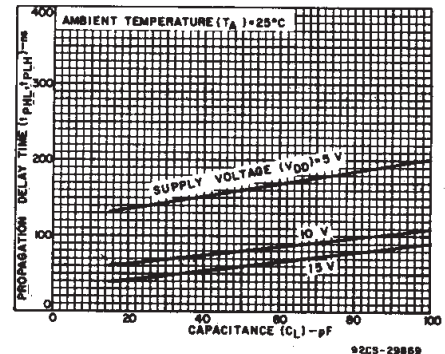


Fig. 8 - Typical propagation delay time as a function of load capacitance.

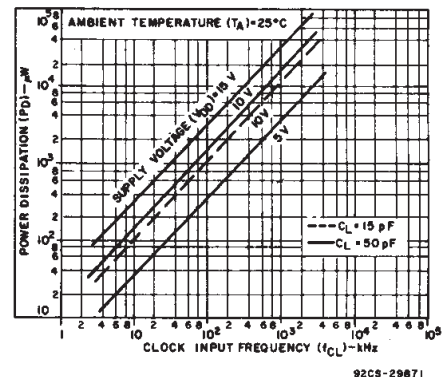


Fig. 9 - Typical dynamic power dissipation as a function of clock input frequency.

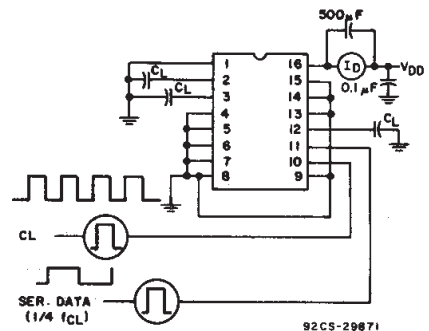


Fig. 10 - Dynamic power dissipation test circuit.

CD4014B, CD4021B Types

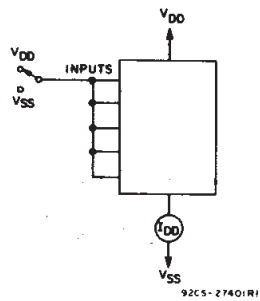


Fig. 11 - Quiescent device current test circuit.

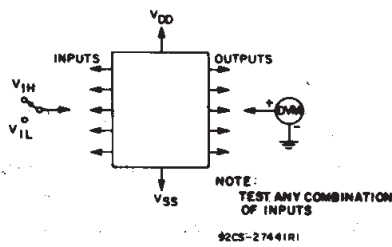


Fig. 12 - Input voltage test circuit.

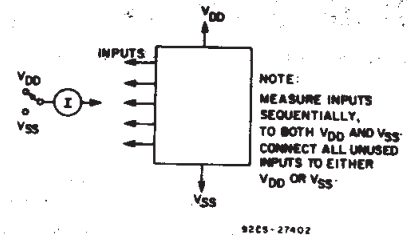
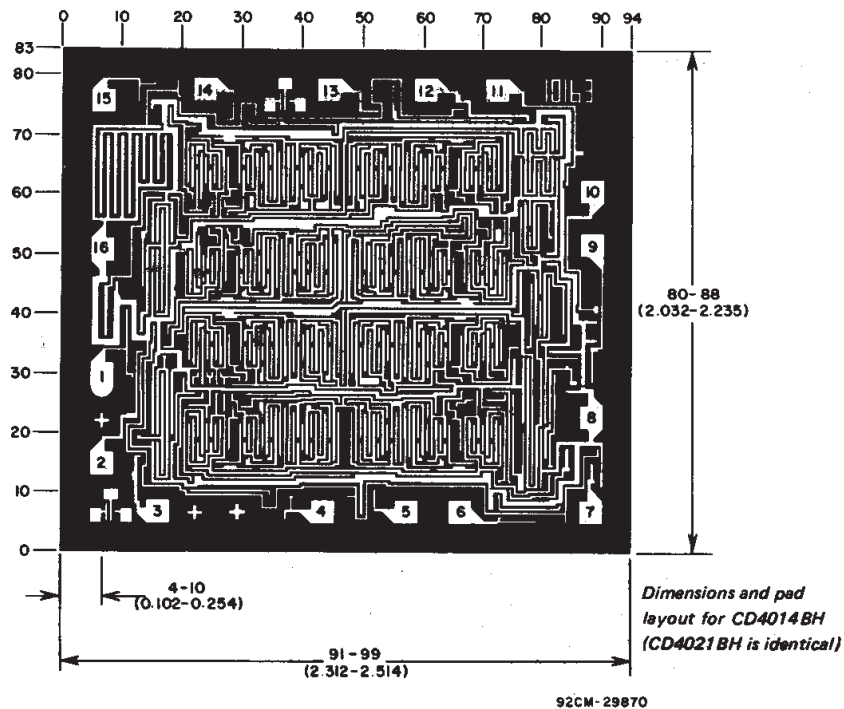


Fig. 13 - Input current test circuit.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

3

COMMERCIAL CMOS
HIGH VOLTAGE ICs

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4014BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4014BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4014BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4014BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4021BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4021BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4021BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4021BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4021BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
JM38510/05754BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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